

SMD Micro Infrared Receiver Module

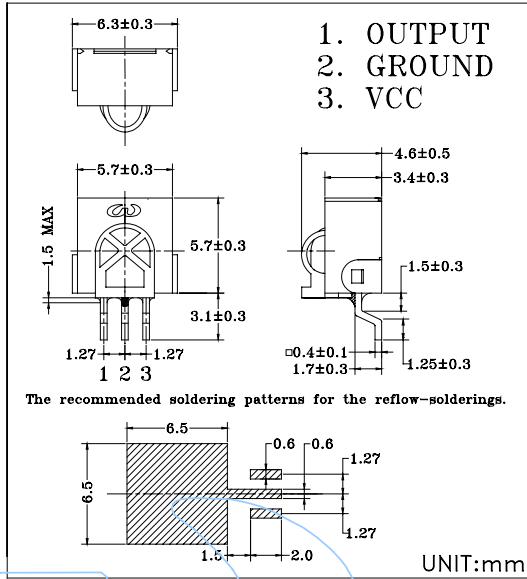
0-05-08-01 Preliminary

Surface Mount Device

Module No.: PIC-5923TMB

Short Pulse Width Acceptable

Dimensions



1. Features:

- Microminiature size
- Built-in exclusive IC
- Wide half angle & long reception distance
- Continuous Signal Acceptable
- Suitable for R-C oscillating transmitter
- High protection ability to EMI
- Back Metal Cover
- Top view
- Mesh
- Wide voltage operating: 2.7V ~ 5.5V

2. Applications

- AV instruments (Audio, TV, VCR, CD player)
- Home appliances (Air-conditioner, Fan, Light.)
- Remote control for wireless devices

3. Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Supply Voltage	Vcc	6.0	V
Operating Temperature	Topr	-10 ~ +60	°C
Storage Temperature	Tstg	-20 ~ +75	°C
Soldering Temperature *1	Tsol	240	°C

*1 At the position of 2mm from the bottom of the package within 5 seconds.

4. Electro-optical Characteristics

(Ta=25°C)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Supply Voltage	Vcc		2.7	3.0	5.5	V
Current Consumption	Icc	Input Signal = 0		1.0	1.5	mA
Reception Distance	d	200±5Lux, Vcc=3.0V	7	10		m
Half Angle (Horizontal)	Δθh			±45		deg
Half Angle (Vertical)	Δθv			+45/-40		deg
Peak Wavelength	λp			940		nm
Signal Output	So		--- Active Low ---			
High Level Output Voltage	Voh		Vcc-0.5			V
Low Level Output Voltage	Vol			0.2	0.4	V
High Level Pulse Width	Twh	Burst Wave = 600μs	500	600	700	μs
Low Level Pulse Width	Twl		500	600	700	μs

5. Reliability Test Items

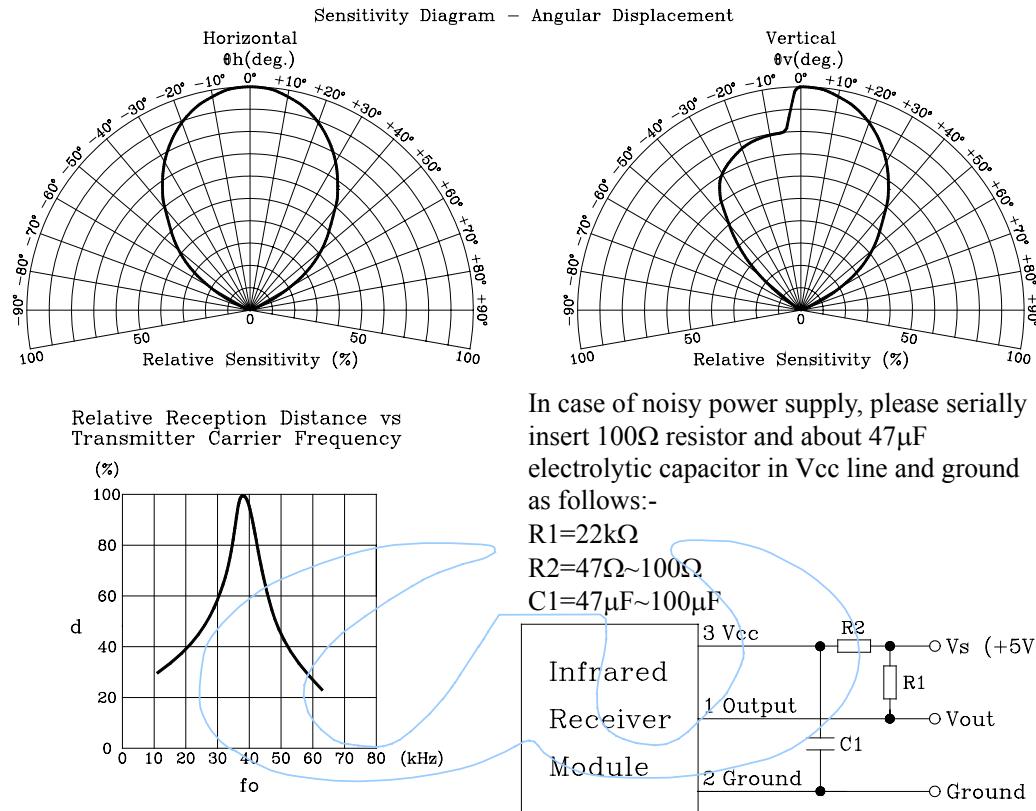
(Ta=25°C)

Test Items	Test Conditions	Ratings
High Temperature Storage	Ta=60°C, Vcc=3.0V	t=240hr.
Low Temperature Storage	Ta=-10°C, Vcc=3.0V	t=240hr.
High Temperature High Humid Storage	Ta=40°C, 90%RH, Vcc=3.0V	t=240hr.
Temperature Cycling	-20°C (30min) ~ +70°C (30min)	20 cycles
Soldering Heat	240±5°C	5 sec.

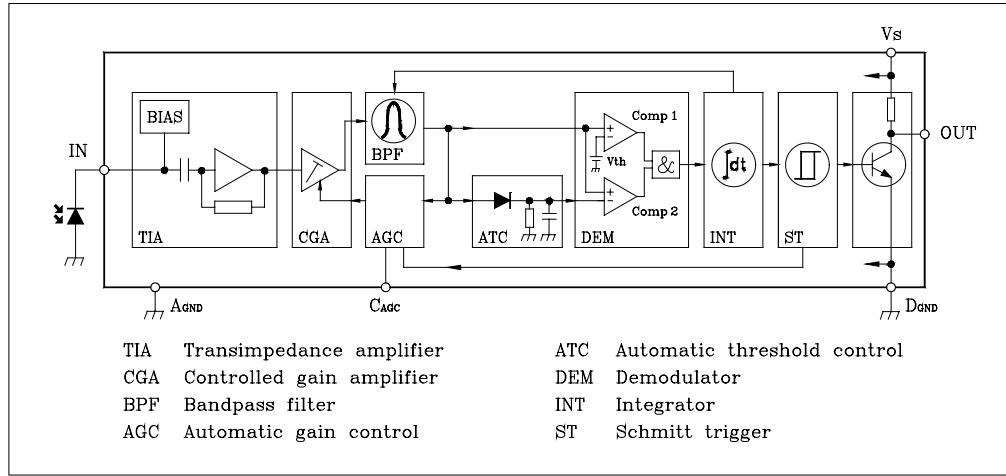
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Block Diagram



Standard Inspection

Among electrical characteristics, total quantity will be inspected as below:-

- Distance between emitter and detector
- Current consumption
- H level output voltage
- L level output voltage

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Testing Method

Distance between emitter and detector specifies maximum distance that output waveform satisfies the standard (FIG-3) under the conditions below against the standard transmitter.

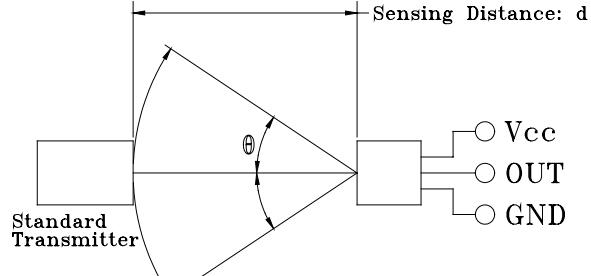


FIG-1

- a. Measuring place
Indoor without extreme reflection of light.

- b. Ambient light source
Detecting surface illumination is 200 ± 5 Lux under ordinary white fluorescence lamp of no high frequency lightning.

- c. Standard transmitter
Transmitter wave indicated in FIG-2 of standard transmitter is arranged to satisfy $V_o \geq 50$ mVp-p under the measuring circuit specified in FIG-3

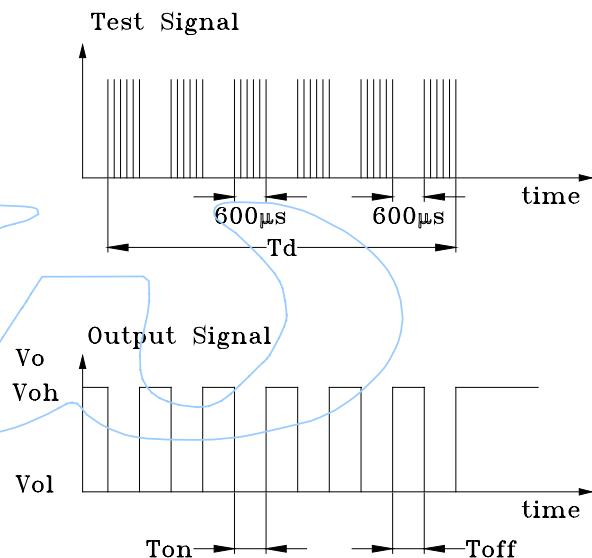


FIG-2

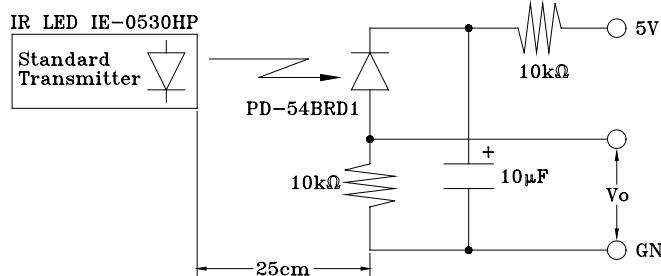


FIG-3 Power Output Measurement Circuit

Precautions for Use

- Store and use where there is no force causing transformation or change in quality.
- Store and use where there is no corrosive gas or sea (salt) breeze.
- Store and use where there is no extreme humidity.
- Solder the lead pin within the condition of ratings. After soldering, do not add exterior force.
- Do not wash this device. Wipe the stains of diode side with a soft cloth. You can use the solvent, ethyl alcohol, or methyl alcohol only.
- To prevent static electricity damage to the pre-amp, make sure that the human body, the soldering iron are connected to ground before using.